

**Features:**

- Isolated mounting base 2500V~
- Pressure contact technology with Increased power cycling capability
- Space and weight saving

Typical Applications

- Inverter
- Inductive heating
- Chopper

V_{RSM}	V_{RRM}	Type & Outline
700V	600V	MZx150-06-413F3D
900V	800V	MZx150-08-413F3D
1100V	1000V	MZx150-10-413F3D
1300V	1200V	MZx150-12-413F3D
1500V	1400V	MZx150-14-413F3D
1700V	1600V	MZx150-16-413F3D
1900V	1800V	MZx150-18-413F3D

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	$T_J(^{\circ}\text{C})$	VALUE			UNIT
				Min	Type	Max	
$I_{F(AV)}$	Mean forward current	180° half sine wave 50Hz Single side cooled, $T_C=100^{\circ}\text{C}$	140			150	A
$I_{F(RMS)}$	RMS forward current					236	A
I_{RRM}	Repetitive peak current	at V_{RRM}	140			30	mA
I_{FSM}	Surge forward current	10ms half sine wave $V_R=0.6V_{RRM}$	140			3.80	kA
I^2t	I^2t for fusing coordination					72	$\text{A}^2\text{s} \cdot 10^3$
V_{FO}	Threshold voltage		140			0.80	V
r_F	Forward slope resistance					1.38	m Ω
V_{FM}	Peak forward voltage	$I_{FM}=450\text{A}$	25			1.60	V
t_{rr}	Reverse recovery time	$I_{FM}=150\text{A}$, $t_p=1000\mu\text{s}$, $-di/dt=20\text{A}/\mu\text{s}$, $V_R=50\text{V}$	140		2.0		μs
$R_{th(j-c)}$	Thermal resistance Junction to case	Single side cooled per chip				0.210	$^{\circ}\text{C}/\text{W}$
$R_{th(c-h)}$	Thermal resistance case to heatsink	Single side cooled per chip				0.040	$^{\circ}\text{C}/\text{W}$
F_m	Terminal connection torque(M8)				12.0		N·m
	Mounting torque(M6)				6.0		N·m
V_{iso}	Isolation voltage	50Hz, R.M.S, $t=1\text{min}$, $I_{iso}=1\text{mA}(\text{MAX})$		2500			V
T_{vj}	Junction temperature			-40		140	$^{\circ}\text{C}$
T_{stg}	Stored temperature			-40		125	$^{\circ}\text{C}$
W_t	Weight				810		g
Outline	413F3D						

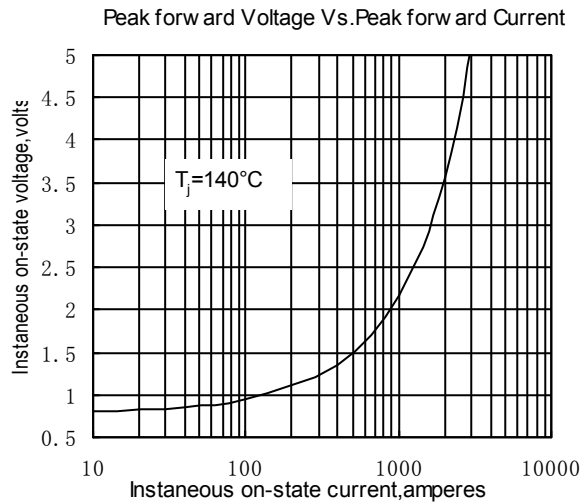


Fig.1

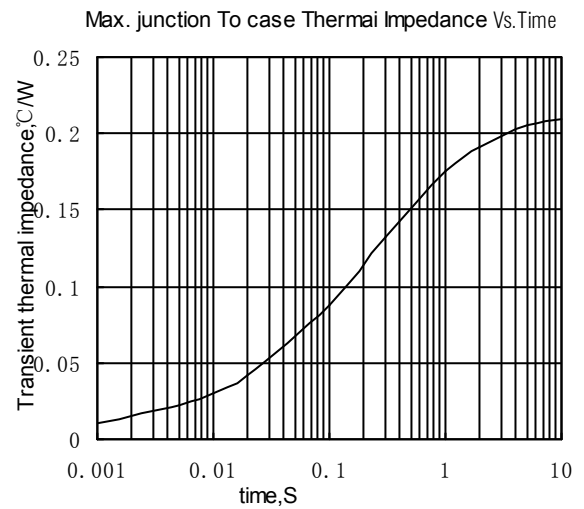


Fig.2

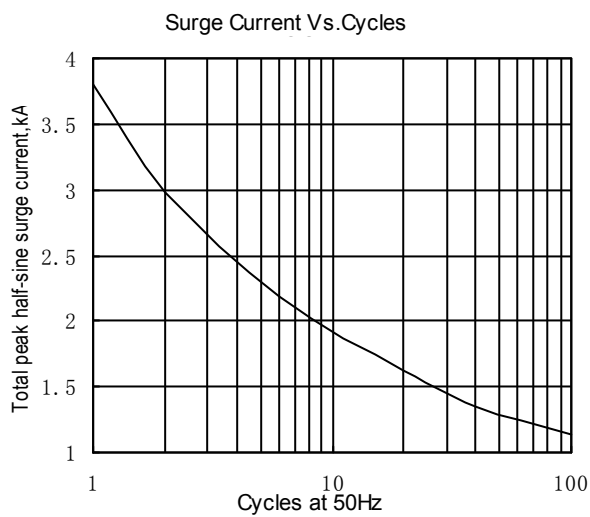


Fig.3

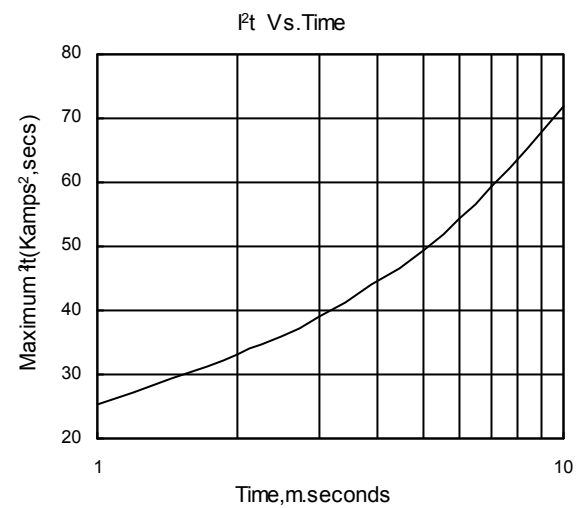


Fig.4

Outline: